Features

- Compatible with MCS-51™ Products
- 1 Kbytes of Reprogrammable Flash Memory
  - Endurance: 1,000 Write/Erase Cycles
  - Data Retention: 10 Years
- 2.7 V to 6 V Operating Range
- Fully Static Operation: 0 Hz to 24 MHz
- Two-Level Program Memory Lock
- 64 bytes SRAM
- 15 Programmable I/O Lines
- One 16-Bit Timer/Counter
- Three Interrupt Sources
- Direct LED Drive Outputs
- On-Chip Analog Comparator
- Low Power Idle and Power Down Modes

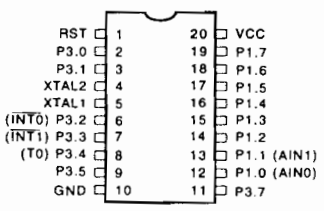
Description

The AT89C1051 is a low-voltage, high-performance CMOS 8-bit microcomputer with 1 Kbytes of Flash programmable and erasable read only memory (PEROM). The device is manufactured using Atmel's high density nonvolatile memory technology and is compatible with the industry standard MCS-51™ instruction set and pinout. By combining a versatile 8-bit CPU with Flash on a monolithic chip, the Atmel AT89C1051 is a powerful microcomputer which provides a highly flexible and cost effective solution to many embedded control applications.

The AT89C1051 provides the following standard features: 1 Kbytes of Flash, 64 bytes of RAM, 15 I/O lines, one 16-bit timer/counter, a five vector two-level interrupt architecture, a precision analog comparator, on-chip oscillator and clock circuitry. In addition, the AT89C1051 is designed with static logic for operation down to zero frequency and supports two software selectable power saving modes. The Idle Mode stops the CPU while allowing the RAM, timer/counters, serial port and interrupt system to continue functioning. The Power Down Mode saves the RAM contents but freezes the oscillator disabling all other chip functions until the next hardware reset.

Pin Configuration

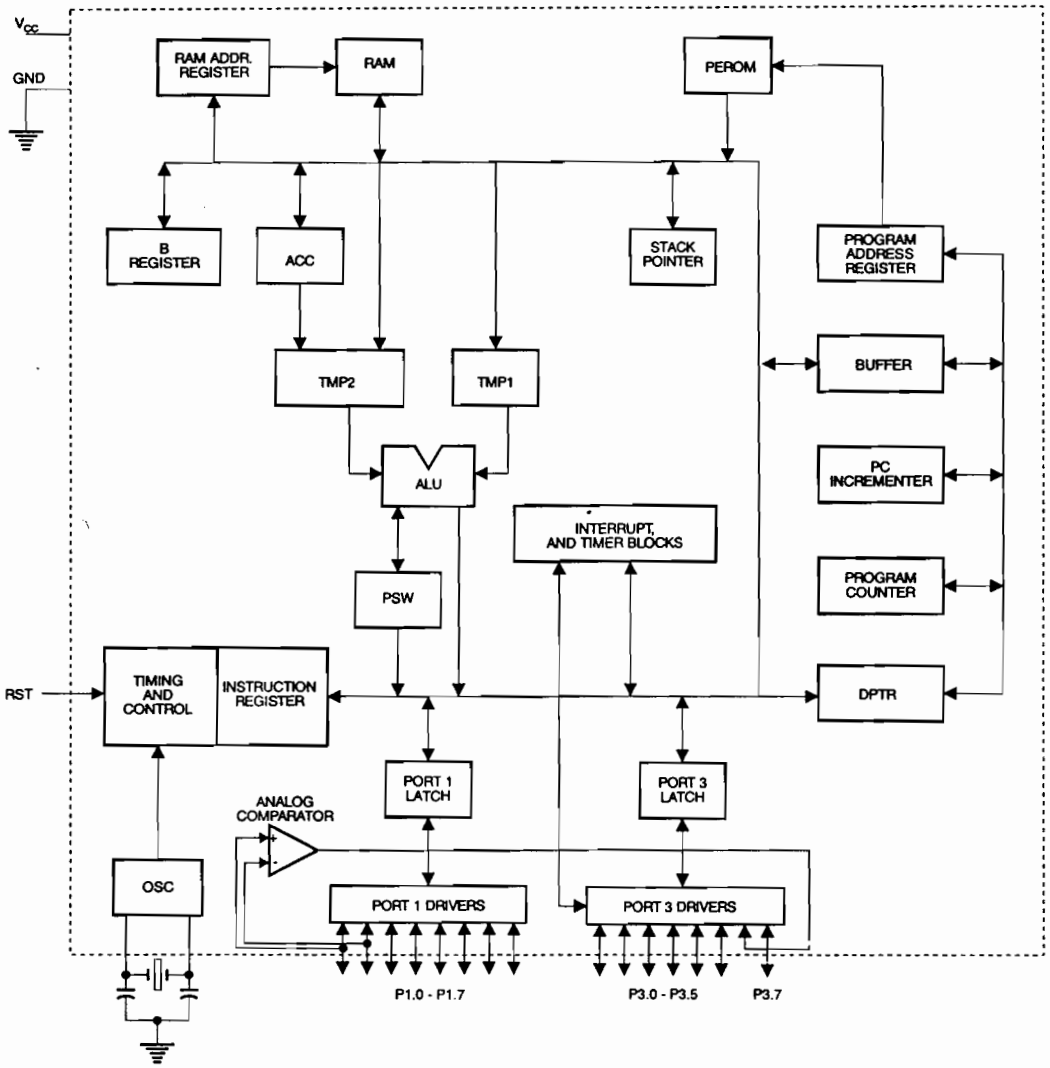
PDIP/SOIC



8-Bit Microcontroller with 1 Kbytes Flash

AT89C1051 Preliminary

Block Diagram



Pin Description

Vcc

Supply voltage.

GND

Ground.

Port 1

Port 1 is an 8-bit bidirectional I/O port. Port pins P1.2 to P1.7 provide internal pullups. P1.0 and P1.1 require external pullups. P1.0 and P1.1 also serve as the positive input (AIN0) and the negative input (AIN1), respectively, of the on-chip precision analog comparator. The Port 1 output buffers can sink 20 mA and can drive LED displays directly. When 1s are written to Port 1 pins, they can be used as inputs. When pins P1.2 to P1.7 are used as inputs and are externally pulled low, they will source current (IIL) because of the internal pullups.

Port 1 also receives code data during Flash programming and program verification.

Port 3

Port 3 pins P3.0 to P3.5, P3.7 are seven bidirectional I/O pins with internal pullups. P3.6 is hard-wired as an input to the output of the on-chip comparator and is not accessible as a general purpose I/O pin. The Port 3 output buffers can sink 20 mA. When 1s are written to Port 3 pins they are pulled high by the internal pullups and can be used as inputs. As inputs, Port 3 pins that are externally being pulled low will source current (I_{IL}) because of the pullups.

Port 3 also serves the functions of various special features of the AT89C1051 as listed below:

Port Pin	Alternate Functions
P3.2	$\overline{INT0}$ (external interrupt 0)
P3.3	$\overline{INT1}$ (external interrupt 1)
P3.4	T0 (timer 0 external input)

Port 3 also receives some control signals for Flash programming and programming verification.

RST

Reset input. All I/O pins are reset to 1s as soon as RST goes high. Holding the RST pin high for two machine cycles while the oscillator is running resets the device.

XTAL1

Input to the inverting oscillator amplifier and input to the internal clock operating circuit.

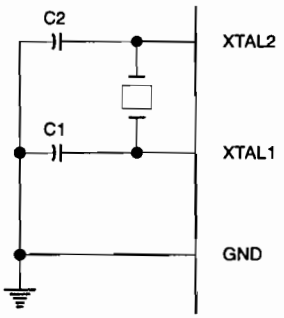
XTAL2

Output from the inverting oscillator amplifier.

Oscillator Characteristics

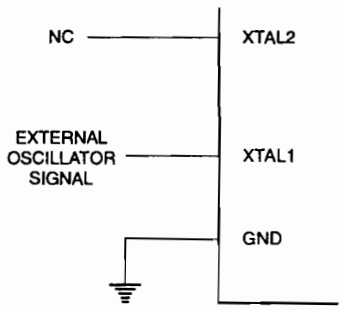
XTAL1 and XTAL2 are the input and output, respectively, of an inverting amplifier which can be configured for use as an on-chip oscillator, as shown in Figure 1. Either a quartz crystal or ceramic resonator may be used. To drive the device from an external clock source, XTAL2 should be left unconnected while XTAL1 is driven as shown in Figure 2. There are no requirements on the duty cycle of the external clock signal, since the input to the internal clocking circuitry is through a divide-by-two flip-flop, but minimum and maximum voltage high and low time specifications must be observed.

Figure 1. Oscillator Connections



Notes: C1, C2 = 30 pF ± 10 pF for Crystals
= 40 pF ± 10 pF for Ceramic Resonators

Figure 2. External Clock Drive Configuration



Special Function Registers

A map of the on-chip memory area called the Special Function Register (SFR) space is shown in the table below.

Note that not all of the addresses are occupied, and unoccupied addresses may not be implemented on the chip. Read accesses to these addresses will in general return random data, and write accesses will have an indeterminate effect.

User software should not write 1s to these unlisted locations, since they may be used in future products to invoke new features. In that case, the reset or inactive values of the new bits will always be 0.

Table 1. AT89C1051 SFR Map and Reset Values

0F8H									0FFH
0F0H	B 00000000								0F7H
0E8H									0EFH
0E0H	ACC 00000000								0E7H
0D8H									0DFH
0D0H	PSW 00000000								0D7H
0C8H									0CFH
0C0H									0C7H
0B8H	IP X0000000								0BFH
0B0H	P3 11111111								0B7H
0A8H	IE 00000000								0AFH
0A0H									0A7H
98H									9FH
90H	P1 11111111								97H
88H	TCON 00000000	TMOD 00000000	TL0 00000000		TH0 00000000				8FH
80H		SP 00000111	DPL 00000000	DPH 00000000				PCON 00000000	87H

Program Memory Lock Bits

On the chip are two lock bits which can be left unprogrammed (U) or can be programmed (P) to obtain the additional features listed in the table below:

Lock Bit Protection Modes[1]

Program Lock Bits			
	LB1	LB2	Protection Type
1	U	U	No program lock features.
2	P	U	Further programming of the Flash is disabled.
3	P	P	Same as mode 2, also verify is disabled.

Note: 1. The Lock Bits can only be erased with the Chip Erase operation

Idle Mode

In idle mode, the CPU puts itself to sleep while all the on-chip peripherals remain active. The mode is invoked by software. The content of the on-chip RAM and all the special functions registers remain unchanged during this mode. The idle mode can be terminated by any enabled interrupt or by a hardware reset.

P1.0 and P1.1 should be set to '0' if no external pullups are used, or set to '1' if external pullups are used.

It should be noted that when idle is terminated by a hardware reset, the device normally resumes program execution, from where it left off, up to two machine cycles before the internal reset algorithm takes control. On-chip hardware inhibits access to internal RAM in this event, but access to the port pins is not inhibited. To eliminate the possibility of an unexpected write to a port pin when Idle is terminated by reset, the instruction following the one that invokes Idle should not be one that writes to a port pin or to external memory.

Power Down Mode

In the power down mode the oscillator is stopped, and the instruction that invokes power down is the last instruction executed. The on-chip RAM and Special Function Registers retain their values until the power down mode is terminated. The only exit from power down is a hardware reset. Reset redefines the SFRs but does not change the on-chip RAM. The reset should not be activated before V_{CC} is restored to its normal operating level and must be held active long enough to allow the oscillator to restart and stabilize.

P1.0 and P1.1 should be set to '0' if no external pullups are used, or set to '1' if external pullups are used.

Programming The Flash

The AT89C1051 is shipped with the 2 Kbytes of on-chip PEROM code memory array in the erased state (i.e., contents = FFH) and ready to be programmed. The code memory array is programmed one byte at a time. *Once the array is programmed, to re-program any non-blank byte, the entire memory array needs to be erased electrically.*

Internal Address Counter: The AT89C1051 contains an internal PEROM address counter which is always reset to 000H on the rising edge of RST and is advanced by applying a positive going pulse to pin XTAL1.

Programming Algorithm: To program the AT89C1051, the following sequence is recommended.

1. Power-up sequence:
   Apply power between V_{CC} and GND pins
   Set RST and XTAL1 to GND
   With all other pins floating, wait for greater than 10 milliseconds
2. Set pin RST to 'H'
   Set pin P3.2 to 'H'
3. Apply the appropriate combination of 'H' or 'L' logic levels to pins P3.3, P3.4, P3.5, P3.7 to select one of the programming operations shown in the PEROM Programming Modes table.

To Program and Verify the Array:

4. Apply data for Code byte at location 000H to P1.0 to P1.7.
5. Raise RST to 12V to enable programming.
6. Pulse P3.2 once to program a byte in the PEROM array or the lock bits. The byte-write cycle is self-timed and typically takes 1.2 ms.
7. To verify the programmed data, lower RST from 12V to logic 'H' level and set pins P3.3 to P3.7 to the appropiate levels. Output data can be read at the port P1 pins.
8. To program a byte at the next address location, pulse XTAL1 pin once to advance the internal address counter. Apply new data to the port P1 pins.
9. Repeat steps 5 through 8, changing data and advancing the address counter for the entire 2 Kbytes array or until the end of the object file is reached.
10. Power-off sequence:
    set XTAL1 to 'L'
    set RST to 'L'
    Float all other I/O pins
    Turn Vcc power off

Data Polling: The AT89C1051 features Data Polling to indicate the end of a write cycle. During a write cycle, an attempted read of the last byte written will result in the complement of the written data on P1.7. Once the write cycle has been completed, true data is valid on all outputs, and the next cycle may begin. Data Polling may begin any time after a write cycle has been initiated.

Ready/Busy: The Progress of byte programming can also be monitored by the RDY/BSY output signal. Pin P3.1 is pulled low after P3.2 goes High during programming to indicate BUSY. P3.1 is pulled High again when programming is done to indicate READY.

Program Verify: If lock bits LB1 and LB2 have not been programmed code data can be read back via the data lines for verification:

1. Reset the internal address counter to 000H by bringing RST from 'L' to 'H'.
2. Apply the appropriate control signals for Read Code data and read the output data at the port P1 pins.
3. Pulse pin XTAL1 once to advance the internal address counter.
4. Read the next code data byte at the port P1 pins.
5. Repeat steps 3 and 4 until the entire array is read.

The lock bits cannot be verified directly. Verification of the lock bits is achieved by observing that their features are enabled.

Chip Erase: The entire PEROM array (2 Kbytes) and the two Lock Bits are erased electrically by using the proper combination of control signals and by holding P3.2 low for 10 ms. The code array is written with all "1"s in the Chip Erase operation and must be executed before any non-blank memory byte can be re-programmed.

Reading the Signature Bytes: The signature bytes are read by the same procedure as a normal verification of locations 000H, 001H, and 002H, except that P3.5 and P3.7 must be pulled to a logic low. The values returned are as follows.

(000H) = 1EH indicates manufactured by Atmel
(001H) = 21H indicates 89C1051
(002H) = FFH indicates 12 V programming

Flash Programming Modes

Mode	RST	P3.2/PROG	P3.3	P3.4	P3.5	P3.7
Write Code Data(1,3)	12V	⌐‾	L	H	H	H
Read Code Data(1)	H	H	L	L	H	H
Write Lock Bit - 1	12V	⌐‾	H	H	H	H
Bit - 2	12V	⌐‾	H	H	L	L
Chip Erase	12V	⌐‾(2)	H	L	L	L
Read Signature Byte	H	H	L	L	L	L

Notes: 1. The internal PEROM address counter is reset to 000H on the rising edge of RST and is advanced by a positive pulse at XTAL1 pin.
2. Chip Erase requires a 10 ms PROG pulse.
3. P3.1 is pulled Low during programming to indicate RDY/BSY.

Figure 3. Programming the Flash Memory

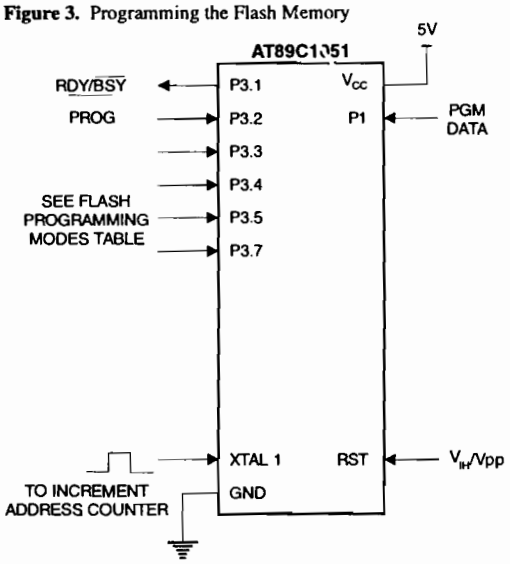
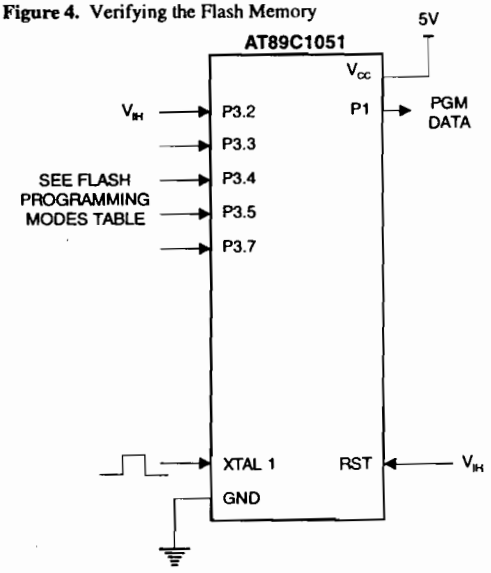


Figure 4. Verifying the Flash Memory

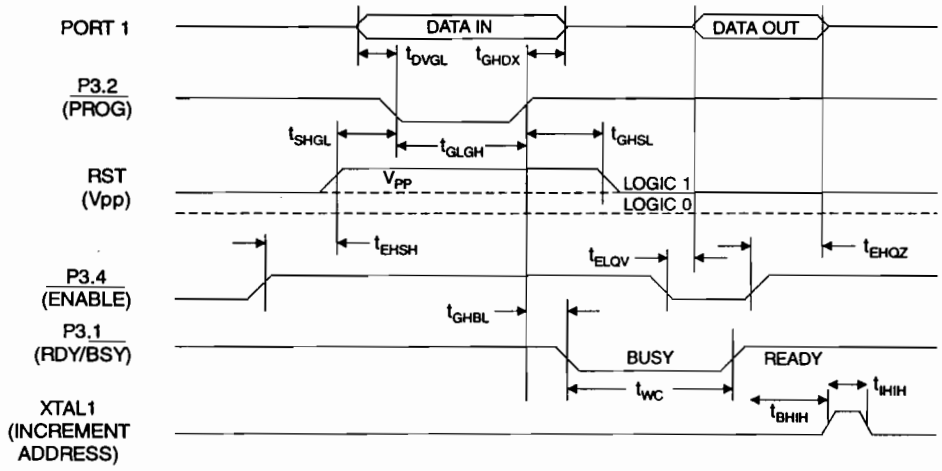


Flash Programming and Verification Characteristics

T_A = 21°C to 27°C, V_{CC} = 5.0 ± 10%

Symbol	Parameter	Min	Max	Units
V_{PP}	Programming Enable Voltage	11.5	12.5	V
I_{PP}	Programming Enable Current		150	µA
t_{DVGL}	Data Setup to $\overline{PROG}$ Low	1.0		µs
t_{GHDX}	Data Hold After $\overline{PROG}$	1.0		µs
t_{EHSH}	P3.4 ($\overline{ENABLE}$) High to V_{PP}	1.0		µs
t_{SHGL}	V_{PP} Setup to $\overline{PROG}$ Low	10		µs
t_{GHSL}	V_{PP} Hold After $\overline{PROG}$	10		µs
t_{GLGH}	$\overline{PROG}$ Width	1	110	µs
t_{ELQV}	$\overline{ENABLE}$ Low to Data Valid		1.0	µs
t_{EHQZ}	Data Float After $\overline{ENABLE}$	0	1.0	µs
t_{GHBL}	$\overline{PROG}$ High to $\overline{BUSY}$ Low		50	ns
t_{WC}	Byte Write Cycle Time		2.0	ms
t_{BHIH}	RDY/$\overline{BSY}$ to Increment Clock Delay	1.0		µs
t_{IHIL}	Increment Clock High	200		ns

Flash Programming and Verification Waveforms



Absolute Maximum Ratings*

Operating Temperature	-55°C to +125°C
Storage Temperature	-65°C to +150°C
Voltage on Any Pin with Respect to Ground	-1.0 V to +7.0 V
Maximum Operating Voltage	6.6 V
DC Output Current	25.0 mA

*NOTICE: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

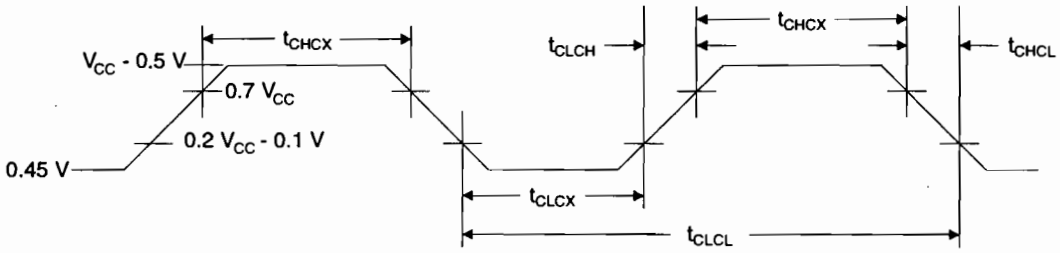
D.C. Characteristics

T_A = -40°C to 85°C, V_{CC} = 2.7 V to 6.0 V (unless otherwise noted)

Symbol	Parameter	Condition	Min	Max	Units
V_{IL}	Input Low Voltage		-0.5	0.2 V_{CC}-0.1	V
V_{IH}	Input High Voltage	(Except XTAL1, RST)	0.2 V_{CC}+0.9	V_{CC}+0.5	V
V_{IH1}	Input High Voltage	(XTAL1, RST)	0.7 V_{CC}	V_{CC}+0.5	V
V_{OL}	Output Low Voltage[1] (Ports 1, 3)	I_{OL} = 20 mA, V_{CC} = 5 V I_{OL} = 10 mA, V_{CC} = 2.7 V		0.45	V
V_{OH}	Output High Voltage (Ports 1, 3)	I_{OH} = -80 µA, V_{CC} = 5 V ± 10%	2.4		V
		I_{OH} = -30 µA	0.75 V_{CC}		V
		I_{OH} = -12 µA	0.9 V_{CC}		V
I_{IL}	Logical 0 Input Current (Ports 1, 2, 3)	V_{IN} = 0.45 V		-50	µA
I_{TL}	Logical 1 to 0 Transition Current (Ports 1, 2, 3)	V_{IN} = 2 V		-750	µA
I_{LI}	Input Leakage Current (Port P1.0, P1.1)	0 < V_{IN} < V_{CC}		±10	µA
V_{OS}	Comparator Input Offset Voltage	V_{CC} = 5 V		20	mV
V_{CM}	Comparator Input Common Mode Voltage		0	V_{CC}	V
RRST	Reset Pulldown Resistor		50	300	KΩ
C_{IO}	Pin Capacitance	Test Freq. = 1 MHz, T_A = 25°C		10	pF
I_{CC}	Power Supply Current	Active Mode, 12 MHz, V_{CC} = 6 V/3 V		20/5.5	mA
		Idle Mode, 12 MHz, V_{CC} = 6 V/3 V P1.0 & P1.1 = 0V or V_{CC}		5/1	mA
	Power Down Mode[2]	V_{CC} = 6 V P1.0 & P1.1 = 0V or V_{CC}		100	µA
		V_{CC} = 3 V P1.0 & P1.1 = 0V or V_{CC}		20	µA

Notes: 1. Under steady state (non-transient) conditions, I_{OL} must be externally limited as follows:
Maximum I_{OL} per port pin: 20 mA
Maximum total IOL for all output pins: 80 mA
If IOL exceeds the test condition, VOL may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.
2. Minimum V_{CC} for Power Down is 2 V.

External Clock Drive Waveforms



External Clock Drive

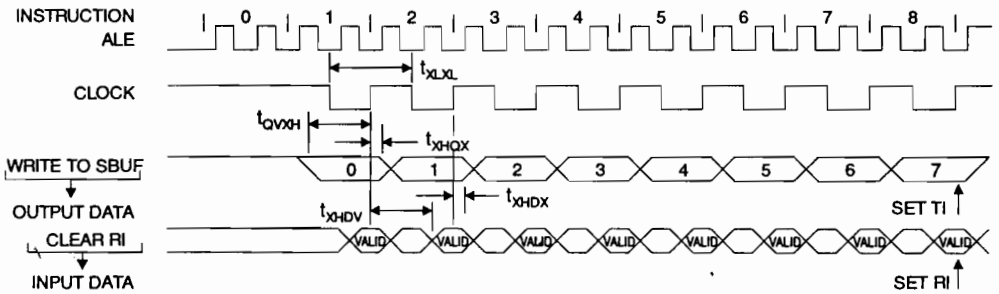
Symbol	Parameter	Min	Max	Units
$1/t_{CLCL}$	Oscillator Frequency	0	24	MHz
t_{CLCL}	Clock Period	41.6		ns
t_{CHCX}	High Time	15		ns
t_{CLCX}	Low Time	15		ns
t_{CLCH}	Rise Time		20	ns
t_{CHCL}	Fall Time		20	ns

Serial Port Timing: Shift Register Mode Test Conditions

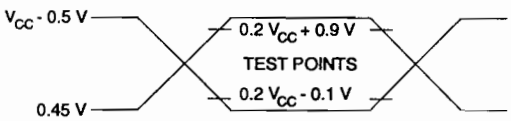
(V_{CC} = 5.0 V ± 20%; Load Capacitance = 80 pF)

Symbol	Parameter	12 MHz Osc		Variable Oscillator		Units
		Min	Max	Min	Max	
t_{XLXL}	Serial Port Clock Cycle Time	1.0		$12t_{CLCL}$		µs
t_{QVXH}	Output Data Setup to Clock Rising Edge	700		$10t_{CLCL}$-133		ns
t_{XHQX}	Output Data Hold After Clock Rising Edge	50		$2t_{CLCL}$-33		ns
t_{XHDX}	Input Data Hold After Clock Rising Edge	0		0		ns
t_{XHDV}	Clock Rising Edge to Input Data Valid		700		10tCLCL-133	ns

Shift Register Mode Timing Waveforms

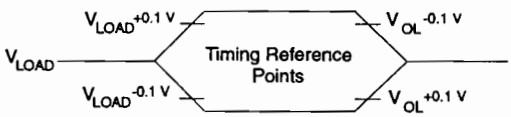


AC Testing Input/Output Waveforms [1]



Note: 1. AC Inputs during testing are driven at V_{CC} - 0.5 V for a logic 1 and 0.45 V for a logic 0. Timing measurements are made at V_{IH} min. for a logic 1 and V_{IL} max. for a logic 0.

Float Waveforms [1]



Note: 1. For timing purposes, a port pin is no longer floating when a 100 mV change from load voltage occurs. A port pin begins to float when a 100 mV change from the loaded V_{OH}/V_{OL} level occurs.

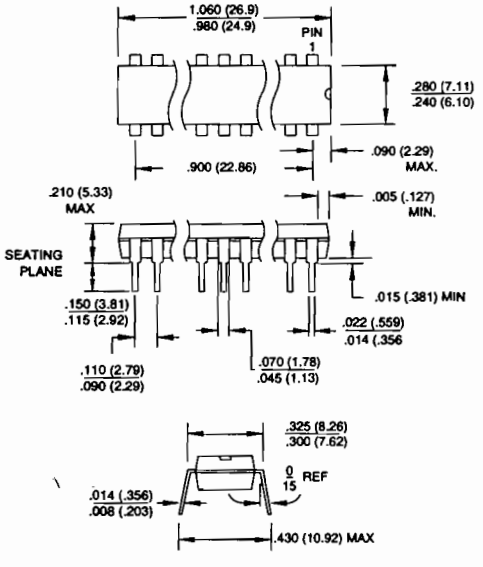
Ordering Information

Speed (MHz)	Power Supply	Ordering Code	Package	Operation Range
12	2.7 V to 6.0 V	AT89C1051-12PC AT89C1051-12SC	20P3 20S	Commercial (0°C to 70°C)
		AT89C1051-12PI AT89C1051-12SI	20P3 20S	Industrial (-40°C to 85°C)
16	3.0 V to 6.0 V	AT89C1051-16PC AT89C1051-16SC	20P3 20S	Commercial (0°C to 70°C)
		AT89C1051-16PI AT89C1051-16SI	20P3 20S	Industrial (-40°C to 85°C)
20	3.3 V to 6.0 V	AT89C1051-20PC AT89C1051-20SC	20P3 20S	Commercial (0°C to 70°C)
		AT89C1051-20PI AT89C1051-20SI	20P3 20S	Industrial (-40°C to 85°C)
24	4.0 V to 6.0 V	AT89C1051-24PC AT89C1051-24SC	20P3 20S	Commercial (0°C to 70°C)
		AT89C1051-24PI AT89C1051-24SI	20P3 20S	Industrial (-40°C to 85°C)
16	4.0 V to 6.0 V	AT89C1051-16PA AT89C1051-16SA	20P3 20S	Automotive (-40°C to 125°C)

Package Type	
20P3	20 Lead, 0.300" Wide, Plastic Dual Inline Package (PDIP)
20S	20 Lead, 0.300" Wide, Plastic Gull Wing Small Outline (SOIC)

Packaging Information

20P3, 20 Lead, 0.300" Wide,
Plastic Dual Inline Package (PDIP)
Dimensions in Inches and (Millimeters)



20S, 20 Lead, 0.300" Wide, Plastic Gull Wing Small Outline (SOIC)
Dimensions in Inches and (Millimeters)